

11. The method of claim 10, wherein the first and second lead portions have an L shape in a cross section of the multilayer body in a length-thickness plane.

12. The method of claim 8, further comprising:

forming dummy lead part patterns on the insulating sheets,

wherein the multilayer body is further formed by stacking the insulating sheets to dispose the dummy lead part patterns to be adjacent to the first and second lead portions, respectively, and to be exposed at surfaces of the multilayer body perpendicular to a stacking surface of the multilayer body.

13. The method of claim 8, wherein the material layer is formed by a plating method or a printing method.

14. The method of claim 8, wherein the internal coil parts are disposed in planes perpendicular to a substrate mounting surface of the multilayer body.

15. The method of claim 8, wherein the forming of the external electrodes further comprises forming the external electrodes on end surfaces of the multilayer body or a bottom surface of the multilayer body.

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